

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2980	(chuck support holder) with temperature with (cool\$3)	US-PGPUB; EPO; JPO; DERWENT	OR	OFF	2005/06/07 11:56
L2	923	1 same (wafer semiconductor substrate)	US-PGPUB; EPO; JPO; DERWENT	OR	OFF	2005/06/07 11:56
L3	283	(chuck support holder) with temperature with (C or ".degree. C") with (cool\$3)	US-PGPUB; EPO; JPO; DERWENT	OR	OFF	2005/06/07 12:34
L4	3	"2002049707"	JPO; DERWENT	OR	OFF	2005/06/07 12:35
S1	52085	(chuck support holder) same (cool\$3)	USPAT	OR	OFF	2005/06/03 13:53
S2	13899	S1 and (wafer semiconductor substrate)	USPAT	OR	OFF	2005/06/03 11:19
S3	2418	S2 and (compensat\$3)	USPAT	OR	OFF	2005/06/03 11:19
S4	126	S1 same compensation	USPAT	OR	OFF	2005/06/03 11:26
S5	22049	118/724 361/234 "269"/\$ 156/345/53 118/712	USPAT	OR	OFF	2005/06/03 11:27
S6	4161	S5 and (cool\$3)	USPAT	OR	OFF	2005/06/03 11:28
S7	1565	S5 and (cool\$3) with (wafer support chuck holder)	USPAT	OR	OFF	2005/06/03 11:28
S8	1557	S7 not S4	USPAT	OR	OFF	2005/06/03 11:28
S9	590	S8 and (coolant cooling) with (fluid liquid line)	USPAT	OR	OFF	2005/06/03 12:06
S10	54020	(dry plasma) with etch\$3	USPAT	OR	OFF	2005/06/03 12:06
S11	1361	S10 and (cool\$3) with (holder chuck support)	USPAT	OR	OFF	2005/06/03 12:07
S12	997	S11 not S8	USPAT	OR	OFF	2005/06/03 12:49
S13	119	temperature same (p near2 n) same (dry plasma) with (etch\$3)	USPAT	OR	OFF	2005/06/03 12:56
S14	798	(P near2 n) with junction with temperature	USPAT	OR	OFF	2005/06/03 12:57
S15	16	(P near2 n) with controller with temperature	USPAT	OR	OFF	2005/06/03 12:57
S16	812	S14 S15	USPAT	OR	OFF	2005/06/03 12:57
S17	750	S16 and (semiconductor wafer substrate)	USPAT	OR	OFF	2005/06/03 12:58
S18	410	S16 same (semiconductor wafer substrate)	USPAT	OR	OFF	2005/06/03 13:02
S19	10	S16 same (holder chuck support)	USPAT	OR	OFF	2005/06/03 13:02
S20	27876	(chuck support holder) same (cool\$3)	EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:02

S21	18481	(chuck support holder) with (cool\$3)	EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:05
S22	1107	S21 same (wafer semiconductor)	EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:04
S23	10	S22 and (pn wiht junction)	EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:04
S24	1	S22 and (pn with junction)	EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:04
S25	1	S22 and pn	EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:04
S26	15299	(chuck support holder) with (cooling coolant)	EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:05
S27	920	S26 same (wafer semiconductor)	EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:47
S28	20723	(coolant cooling) with temperature with C	US-PGPUB; EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:50
S29	473	S28 and (cooling coolant) with (chuck support holder)	US-PGPUB; EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:49
S30	152	S29 and(wafer semiconductor)	US-PGPUB; EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:50
S31	0	(coolant cooling) with temperature with ".degree.C"	US-PGPUB; EPO; JPO; DERWENT	OR	OFF	2005/06/03 14:50